

## CURRENT STATUS OF THE CLAIMS SECTION:

Claims 1-12 (canceled)

Claim 13 (previously presented): A method of producing a ceramic thermistor chip, said method comprising the steps of:

stacking a specified number of thermistor ceramic green sheets;

cutting the stacked ceramic green sheets to obtain a ceramic thermistor element having a specific resistance lower than  $200\Omega\cdot\text{cm}$  and comprising as principal component oxides containing two or more metals selected from the group consisting of Mn, Ni, Co, Fe, Cu and Al, said ceramic thermistor element having outer surfaces including two end parts away from each other;

applying a ceramic material, having a higher specified resistance than said thermistor ceramic green sheets, entirely over said outer surfaces of said ceramic thermistor element except said end parts, wherein said ceramic material comprises same principal component as said ceramic thermistor element, including one or more oxides containing two or more metals selected from the group consisting of Mn, Ni, Co, Fe, Cu and Al and including also at least one metal selected from the group consisting of Zn, Al, W, Zr, Sb, Y, Sm, Ti and Fe;

thereafter baking said ceramic thermistor element together with said ceramic material applied thereon and thereby forming high-resistance layers; and

thereafter subjecting said baked ceramic thermistor element to an electrolytic plating process to thereby form electrolytically plated layers on said end parts whereby said outer surfaces of said ceramic thermistor element are entirely covered by said high-resistance layers except where said electrolytically plated layers are formed.

Claim 14 ((previously presented): The method of claim 13 wherein said ceramic layers and said thermistor element both have said same principal component by 10% or more.

Claim 15 -18 (canceled)

Claim 19 ((previously presented): The method of claim 13 wherein electrolytic plating is prevented from occurring on outer surfaces of said high-resistance layers.

Claim 20 (previously presented): The method of claim 14 wherein electrolytic plating is prevented from occurring on outer surfaces of said high-resistance layers.